



NILPhotonics®

Competence Center

A smart way to collaborate
for success

EVG's equipment solutions and manufacturing process expertise are critical to supporting many applications within the semiconductor industry, with proven success in a variety of key markets, including:

- Advanced Packaging, 3D Interconnect
- MEMS (MicroElectroMechanical Systems)
- SOI (Silicon-On-Insulator)
- Compound Semiconductor and Silicon based Power Devices
- Nanotechnology

Recent developments in nanoimprint lithography (NIL) and wafer bonding offer new capabilities to manufacture innovative photonic structures with the highest functionality, smallest form factors and lowest possible costs.

EVG is strongly committed to the emerging photonics industry, and has recently announced new company initiatives and technologies to facilitate bridging the gap between photonics R&D and volume manufacturing.

EV Group (EVG) offers:

- Wafer Bonders
- Aligners
- Coaters / Developers
- Temporary Bonders / Debonders (Laminators)
- Cleaners
- Inspection Systems



EVG®7200 Automated UV-NIL System up to 200 mm



EVG®HERCULES®NIL Automated SmartNIL® UV Nanoimprint Lithography System up to 200 mm

EVG NILPhotonics® Competence Center at a glance

Our recently established NILPhotonics Competence Center is a flexible cooperation model that leverages the company's equipment and process know-how gained through many years of experience to support the diversified needs of the photonics market.

It is EVG's goal to develop customer and industry partnerships, conjointly overcome challenges and shorten the time to market for innovative photonic devices and applications.

EVG has a particular focus on making the benefits of NIL accessible to the photonics community as it has proven to be an enabling solution for a number of novel photonic devices.

EVG has a global partner network to draw from to support its customers' process integration and optimization efforts across the NIL infrastructure, including template, resist materials and supporting metrology. Multidisciplinary teams provide an in-depth understanding of material interactions and surface chemistry as well as process and equipment requirements for scaling from first feasibility to volume production.

As a result, EVG is able to provide consultation and support during process development and ramp-up to pilot manufacturing.



Cleanroom at EVG headquarters





www.EVGroup.com

Companies and other parties interested in partnering with the NILPhotonics Competence Center can contact EV Group by phone at +43-7712-5311-0 or can e-mail NILPhotonics@EVGroup.com

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